

CMP User's meeting 2017

ams Full Service Foundry division

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2017-01-26, Paris

AMS OVERVIEW & UPDATES

0.18UM PROCESSES

0.30UM SUPER LOW NOISE HV PROCESS (A30)

FOUNDRY OPTOELECTRONIC PLATFORM



ams at a glance







Our business

- Focus on high performance sensor solutions
- Sensor solutions, sensor ICs, interfaces, related software
- Small, low power, highest sensitivity, multi-sensor integration
- Full service foundry including packaging and testing options

Our end markets

- Consumer & Communications (C&C) 50% of sales H1 2016
- Automotive, Industrial, Medical (AIM) 50% of sales H1 2016

By the numbers

- 700+ ams engineers (830+ combined with Heptagon)
- 18+1 design centers, 2+1 manufacturing locations
- 35 years of design and manufacturing know-how
- 2,100+ ams employees worldwide (2,900+ combined with Heptagon)
- 8,000+ customers



The ams world of sensors

Smart Phones & Tablet



- Ambient light, color & proximity sensors
- Active Noise Cancellation
- Breath analysis
- Gesture recognition
- Environmental sensors
- Spectral sensors

Wearables



- Biosensors, heart rate monitoring
- Active Noise Cancellation
- Environmental sensors
- Ambient light, color sensing
- Power management

Smart Home & Buildings



- · Air quality sensors
- Flow sensors
- Gas sensors
- Humidity sensors
- · Smart light sensors
- Temperature sensors

Automotive







Industrial

- CMOS sensors for machine vision and drones
- Flow sensors
- Industrial/building automation
- NFC/RFID Sensor Tags
- Position sensors



Medical

- CMOS image sensors and miniature cameras for endoscopy
- Image Sensors for:
 - Computed tomography
 - Digital x-ray
 - Surgical robots



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Full service foundry

Your one-stop-shop for turn-key high performance analog IC solutions









Specialty processes

- 0.18μm, 0.35μm, 0.8μm
 MPW & MLR service
- CMOS, HV, SiGe
- AUT & MED certified
- Extended temp range

Foundry services

- Benchmark PDK: hitkit
 Mixed-signal test
- Highly accurate models
 Qualification services
- Digital & analog base IP
 2nd source capabilities

Turn-key solutions

- One-stop-shop

More than silicon

- Customized solutions
- 3D IC using TSVs
- Extended IP portfolio
- Advanced packages



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Status of 0.18µm processes

Technology	C18	H18
status	released	released
hitkit	v4.11 released	v4.11 released
design documents	released	released
MPW runs	available	available
SDT runs	available	available
production	mass prod	mass prod



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Technology	C18	H18	aC18	aH18
status	released	released	cond. released	May 2017
hitkit	v4.11 released	v4.11 released	v4.14 released	v4.14 on demand
design documents	released	released	released	prel. docs on demand
MPW runs	on demand	on demand	4 runs in 2017	4 runs in 2017
SDT runs	available	available	available	accepted
production	mass prod	mass prod	ramp up	N.A.

- → All information available on foundry support server!
- → Please contact hitkit@ams.com



C18/H18 vs. aC18/aH18 process

Process migration

Device:

- Not all devices are available at ams
- BE stack different (CU vs. AL, FT, AM)
- Different models / corners
- HV oxide not available
- New IOLIBs

Action:

re-simulate / replace

redesign

re-simulate

redesign

redesign

- → Migration guidelines and support available for foundry customers
- → Please contact hitkit@ams.com



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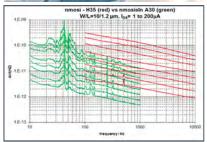


A30 – 0.30µm Analog Low Noise CMOS process

High performance CMOS process optimized for ultra low noise applications







Technology highlights

- based on industry proven 0.35µm High-Voltage CMOS process
- realized as an optical shrink by a factor of 0.9 from H35
- 3 and 4 metal layers, optional thick top metal 4 available

Extensive set of high quality devices:

- Optimized super low noise device **NMOSISLN** (noise: 0.46 pA/ \sqrt{Hz})
- Isolated HV NMOSI20T device
- Floating 3.3V NMOS/PMOS (std. V_T and low V_T)
- Vertical bipolar devices VERTN1/VERTPH
- Several capacitors (poly, sandwich, MOS varactor)
- Several resistors (poly, high-res poly, precision poly, diffusion, well)

Advantages & benefits:

- Superior noise performance
- Smaller die size / more dies per wafer
- High yield: Running in mass production (billions of devices shipped)



Applications & Markets A30 HPA Low Noise CMOS Process

Market	Application	Device Features & Requirements	
Medical	Hearing Aid	Audio signal (amplifier), Noise cancelling	
Medical	Neural Recording	Low Noise Amplifier	
Consumer	Mobile ANC	Headsets, MEMS Micro Amplifier	
Automotive	ANC	Cabin Noise Cancelling	



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Foundry Optoelectronic Platform

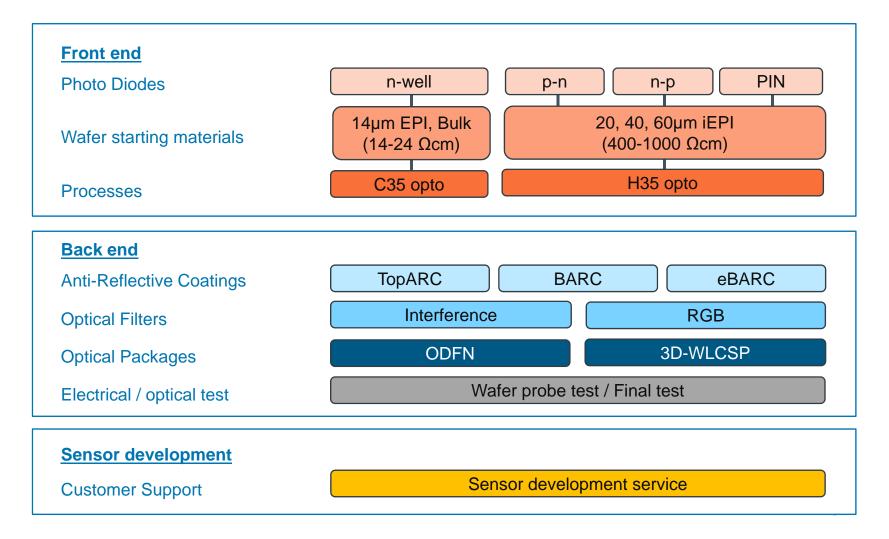
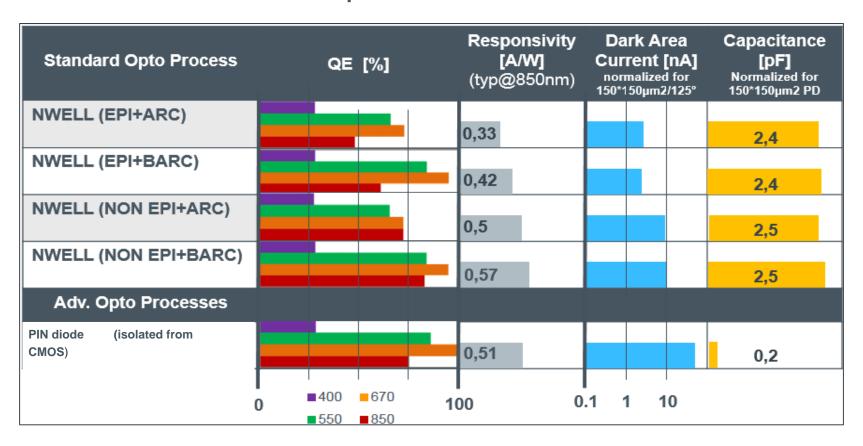




Photo Diodes / Examples



N-well and PIN photo diodes with different performances in responsivity, dark current and capacities depending on wafer material, ARC or BARC.



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Shaping the world with sensor solutions

Advanced analog & mixed-signal semiconductor ecosystem

PDK

- HD Digital libraries
- IO cells incl ESD protection structures
- Verification rule decks (DRC, LVS, ERC, PEX, ..)
- Various tools: SOAC, LTACC

IPs & Advanced IPs

- ADCs & DACs
- Bandgaps
- RAMs & ROMS
- OTPs & EEPROM blocks

Consulting Services & Support

- Design Support
- ESD support
- · Place & Route

Turnkey Solutions

- Test program & hardware development
- · Wafer sort & final test
- Assembly services

3rd Party IP Blocks

- · LDOs, Oscillators, PLLs
- ADCs & DACs
- Custom IP block development

Design Resources

- Block level design
- Complete IC design

Product Qualification

- HTOL & HAST
- APQP
- PPAP

3D-IC technologies

- Through Silicon Vias (TSV)
- · Wafer to wafer bonding
- Die to wafer stacking

EDA Tool Support

- Access to 3rd party PDKs
- EDA tool service



Thank you

Please visit our website www.ams.com